

MECHANICAL CASE OUTLINE

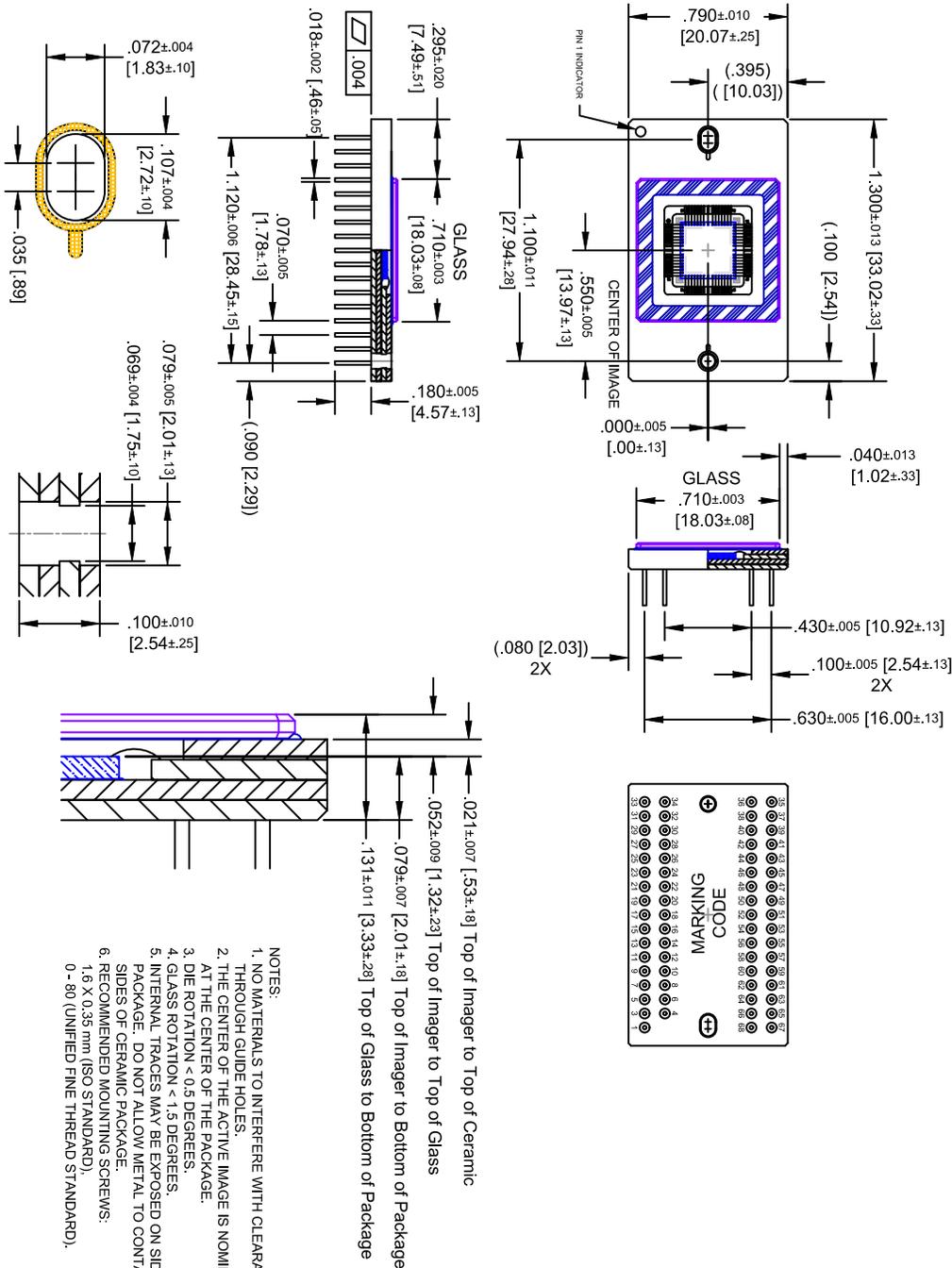
PACKAGE DIMENSIONS

ON Semiconductor®



CPGA67, 33.02x20.07 CASE 107EG ISSUE O

DATE 30 JUL 2014



- NOTES:
1. NO MATERIALS TO INTERFERE WITH CLEARANCE THROUGH GUIDE HOLES.
 2. THE CENTER OF THE ACTIVE IMAGE IS NOMINALLY AT THE CENTER OF THE PACKAGE.
 3. DIE ROTATION < 0.5 DEGREES.
 4. GLASS ROTATION < 1.5 DEGREES.
 5. INTERNAL TRACES MAY BE EXPOSED ON SIDES OF PACKAGE. DO NOT ALLOW METAL TO CONTACT SIDES OF CERAMIC PACKAGE.
 6. RECOMMENDED MOUNTING SCREWS: 1.6 X 0.35 mm (ISO STANDARD), 0 - 80 (UNIFIED FINE THREAD STANDARD).

Dimensions in: Inches [mm]

DOCUMENT NUMBER:	98AON88256F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CPGA67, 33.02x20.07	PAGE 1 OF 2

